

Connector for microSD™ Card (Push-push Ejection Type)

SCHA Series



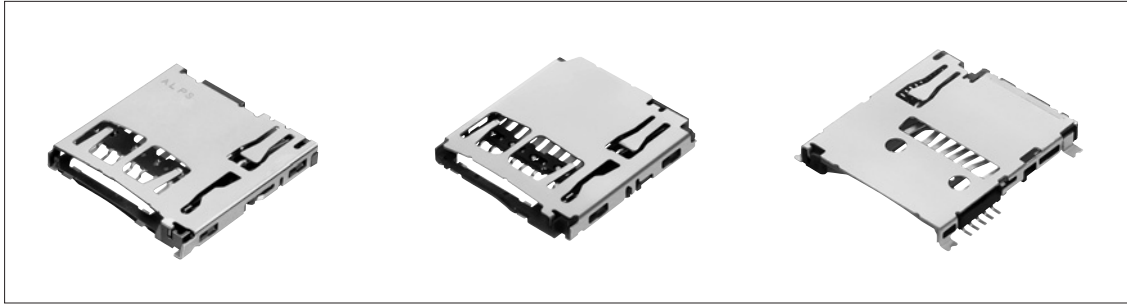
Compact low-profile type most suitable for cell phones.

For SD Memory Card

For miniSD™ Card

For microSD™ Card

For W-SIM



For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Features

- Improved operability from a clear click feel.
- Good operational feel.

Applications

- For mobile phones, personal digital assistants, digital still cameras, compact audio equipment.

Typical Specifications

Items		Specifications	
Structure	Applicable media	microSD™ Card	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount/Reverse mount	
	Media ejection structure	Push-push type	
Performance	Operating temperature range	-20°C to +70°C	
	Voltage proof	500V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle	5,000cycles		

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without switch	0	Taping	SCHA1A0101	1
		With switch			SCHA1B0100	2
	Reverse mount	SCHA2B0300			3	

Dimensions
Standard mount

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	<p>Without switch</p>	
2	<p>With switch</p>	

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Dimensions
Reverse mount

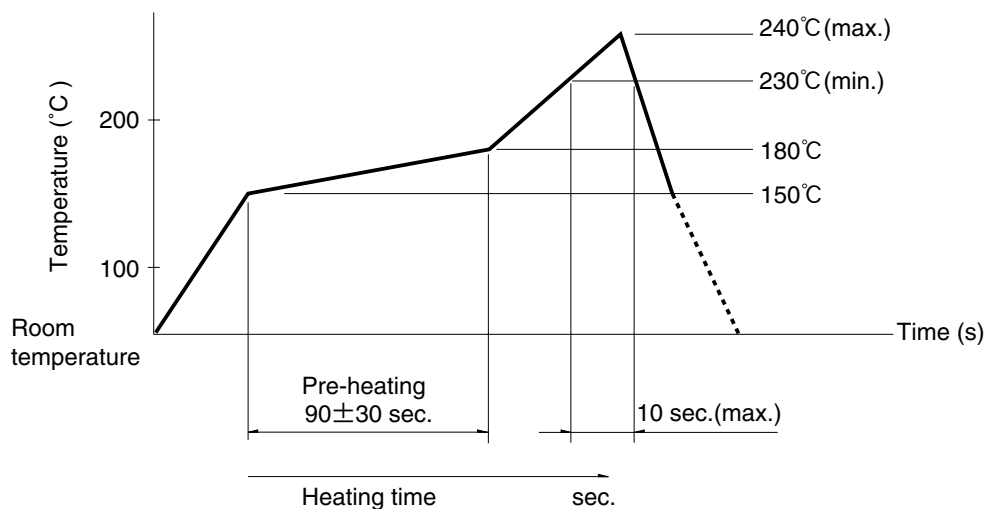
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No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. This product has been designed and manufactured for use in ordinary electronic equipment, such as AV equipment, electric home appliances, office machines and communication equipment. In case of using the products for highly sensitive applications such as medical, aviation, aerospace and security, the set makers shall require to include measures necessary to meet product safety requirements of such specific applications. Such measure may include additional protection circuits and redundant circuits, for example.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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